



# SOT1089

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

9 January 2017

Package information

## 1. Package summary

<b>Dimensions (mm)</b>	1.35 x 1 x 0.5
<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	XSON8
<b>Package outline version code</b>	SOT1089
<b>Manufacturer package code</b>	SOT1089
<b>Package type industry code</b>	XSON8
<b>Package outline version description</b>	plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package body material type</b>	P
<b>JEDEC package outline code</b>	MO-252
<b>Handling precautions</b>	IC26_CHAPTER_3_2000
<b>Thermal design considerations</b>	IC26_CHAPTER_6_2000
<b>Mounting method type</b>	S (surface mount)
<b>Package life cycle status</b>	REL
<b>Major version date</b>	18-11-2009
<b>Minor version date</b>	10-5-2012
<b>Security status</b>	COMPANY PUBLIC
<b>Modified date</b>	10-5-2012
<b>Issue date</b>	12-4-2010
<b>Web publication date</b>	28-11-2012
<b>Initial web publication date</b>	9-3-2011
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Product
<b>Package author</b>	Nair Deepa
<b>Package approver</b>	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	-	-	-	0.5	mm
D	package length	1.3	-	1.35	1.4	mm
E	package width	0.95	-	1	1.05	mm
e	nominal pitch	-	-	0.55	-	mm



plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

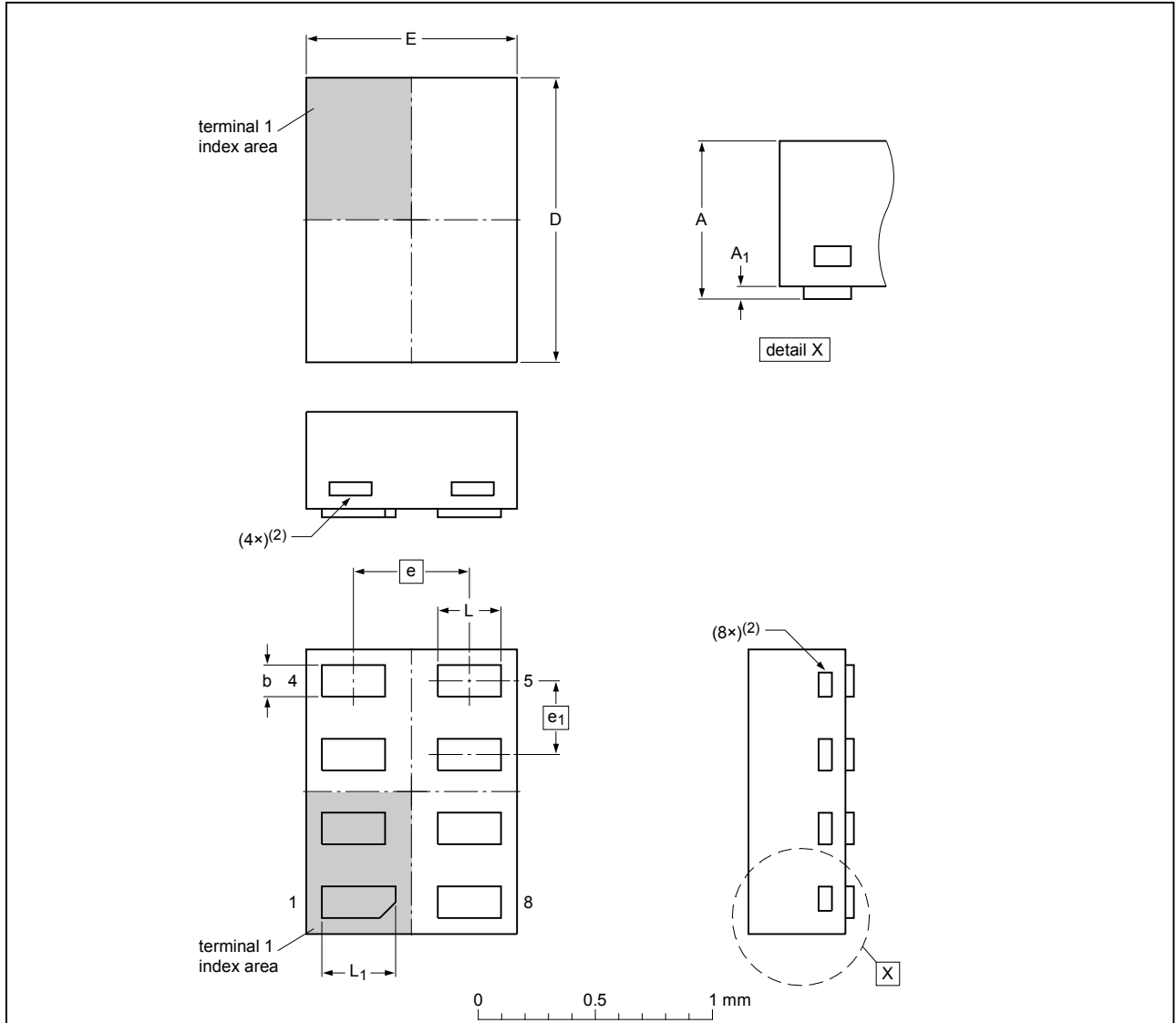
Symbol	Parameter		Min	Typ	Nom	Max	Unit
n <sub>2</sub>	actual quantity of termination		-	-	8	-	

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## 2. Package outline

XSON8: extremely thin small outline package; no leads; 8 terminals; body 1.35 x 1 x 0.5 mm

SOT1089



**Dimensions**

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	max 0.5	0.04	0.20	1.40	1.05	0.55	0.35	0.30	0.35
	nom 0.15	1.35	1.00	0.95					
	min 0.12	1.30	0.95						

**Note**

- Including plating thickness.
- Visible depending upon used manufacturing technology.

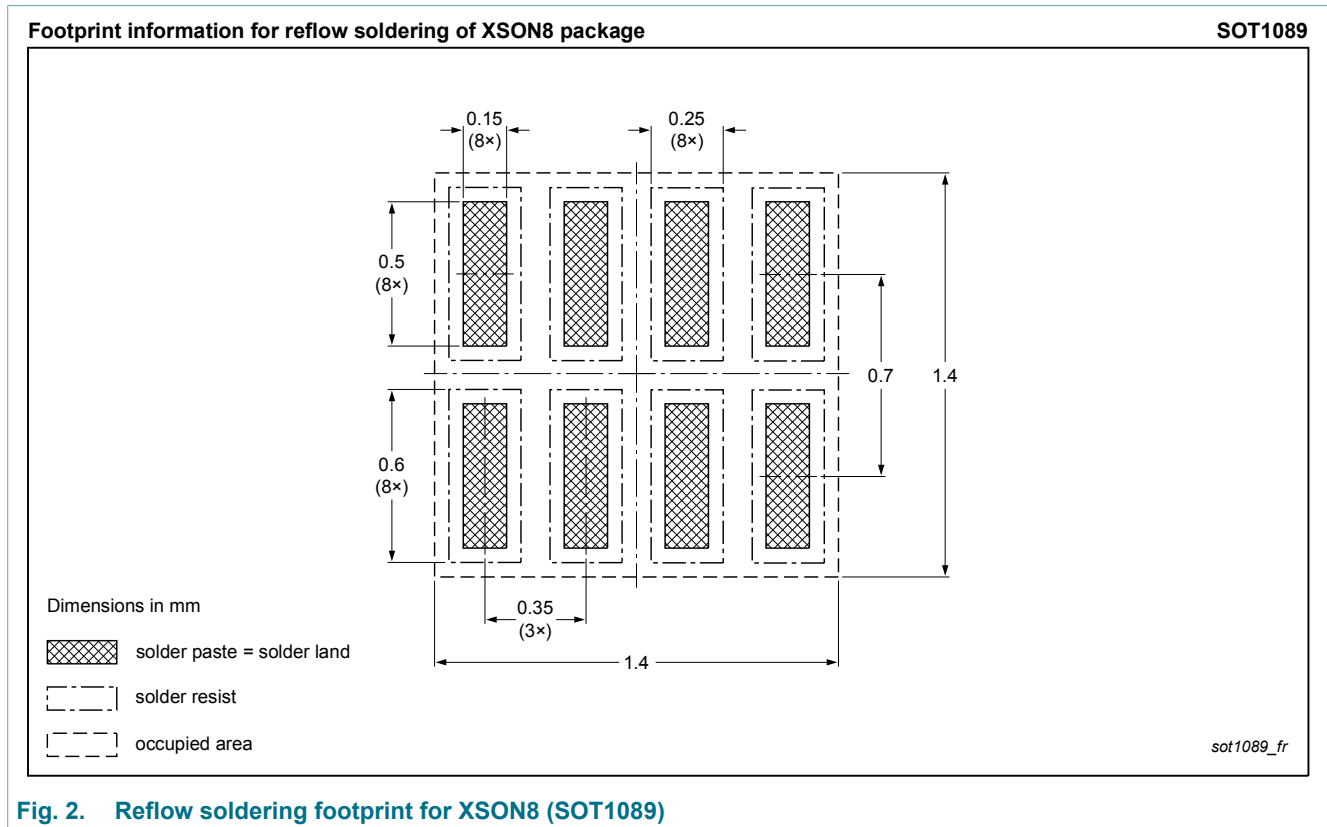
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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1089	MO-252				10-04-09 10-04-12

Fig. 1. Package outline XSON8 (SOT1089)

plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

### 3. Soldering



**Fig. 2. Reflow soldering footprint for XSON8 (SOT1089)**

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plastic, extremely thin small outline package; no leads; 8 terminals; 0.55 mm pitch; 1.35 mm x 1 mm x 0.5 mm body

## 4. Legal information

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Date of release: 9 January 2017

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